

# 46-6063 Economy Version

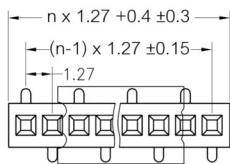
SMT-Buchsenleisten RM 1,27mm, stehend, 1-reihig - durchsteckbar  
SMT Female Headers, 1.27mm Pitch, Vertical, Single Row – Pass Through

## Technische Daten / Technical Data

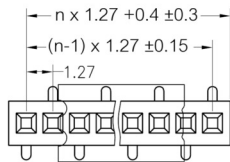
Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ < 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ > 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC/DC 500 V AC/DC
Nennstrom <i>Current Rating</i>	1 A 1 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +105 °C -40 °C ... +105 °C
Verarbeitung <i>Processing</i>	230 °C für 30-60 Sekunden (260 °C für 10 Sekunden) 230 °C for 30-60 seconds (260 °C for 10 seconds)



Doppelfederkontakte für Vierkantstifte 0,40mm.  
Dual beam contacts accept 0.40mm square pins.

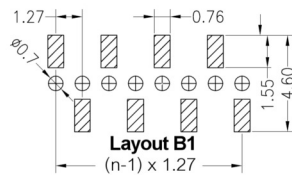


1P Layout B1

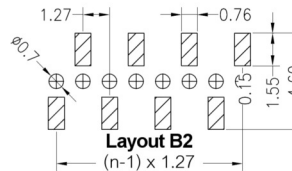


1P Layout B2

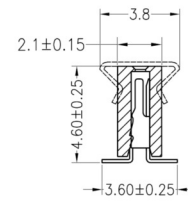
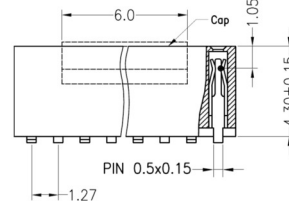
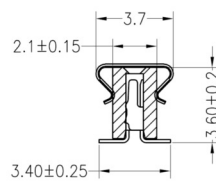
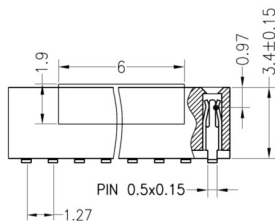
### Recommended PCB Layouts (Top Side) (PCB BOARD TOLERANCE ±0.05)



Layout B1



Layout B2



## Series

**46-6063**

## Contacts\*

**16**

04-36 Einreihig  
Single row

## Layout\*

**1**

1 Einreihig B1  
Single row B1  
2 Einreihig B2  
Single row B2

## Profile\*

**36**

36 H=3,6mm  
46 H=4,6mm

## Plating

**00**

00 Vergoldet  
Gold plated

## Packaging

**MPST**

ST  
MPST  
MPTR

### Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads

MPST In Stangen mit P&P-Pads / In tubes with P&P-Pads

MPTR Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

\* Dies ist ein Bestellbeispiel - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an order example - please replace by your specifications.

# Reflow-Lötverfahren

## Reflow Soldering Information

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	untere Temperaturangabe [°C]
Verweildauer oberhalb $T_L$	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	Lower Temperature [°C]
Duration above $T_L$	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

